

REMARKS

Upon review of the Advisory Action mailed November 28, 2005, Applicants submit the foregoing amendments to place the application in condition for allowance. Specifically, claim 22 has been amended to recite the limitations previously found in claim 24. Accordingly, claim 24, which was indicated as containing allowable subject matter in the Final Rejection dated August 7, 2005, has been canceled. Claims 23, 25, 26, 27 and 28 depend from allowable claim 22. Claim 1-9, 11-15 and 17-36 were previously allowed. Therefore, entry of the amendment and withdrawal of the outstanding rejection are requested. Claims 1-9, 11-15, 17-23, and 25-36 remain pending and are all allowable.

As amended, claim 22 recites "An integrated circuit wafer, comprising: a plurality of dice, each of said dice having a plurality of first platable features; and a plurality of second platable features, wherein each first platable feature is conductively connected to more than one second platable feature, and each of said second platable features is electrically connected to more than one first platable feature and is a probe point for testing said dice." This combination of claim limitations is not taught or suggested by U.S. Patent No. 6,953,951 to Yamazaki et al, recently cited by the Examiner in the Advisory Action dated November 28, 2005.

The foregoing amendments are believed to put the application in condition for immediate allowance. Entry of the amendment and allowance of the application are respectfully requested.

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Respectfully submitted,

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